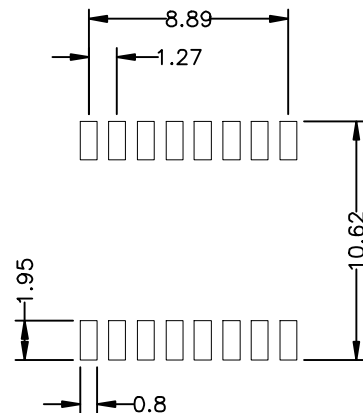
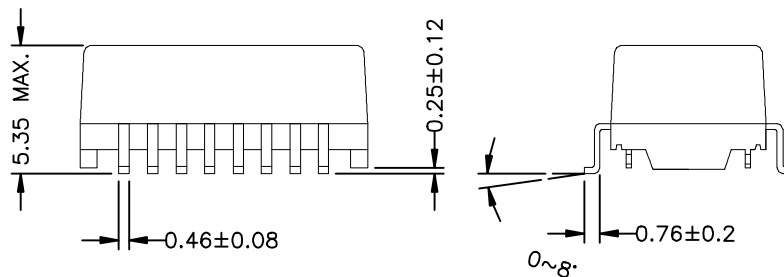
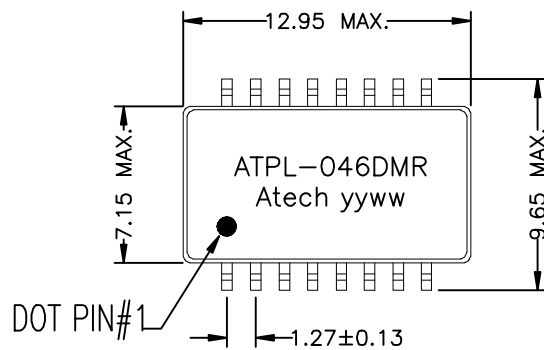
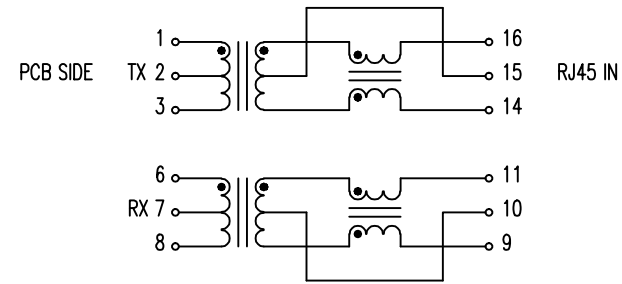




SUGGESTED PAD LAYOUT



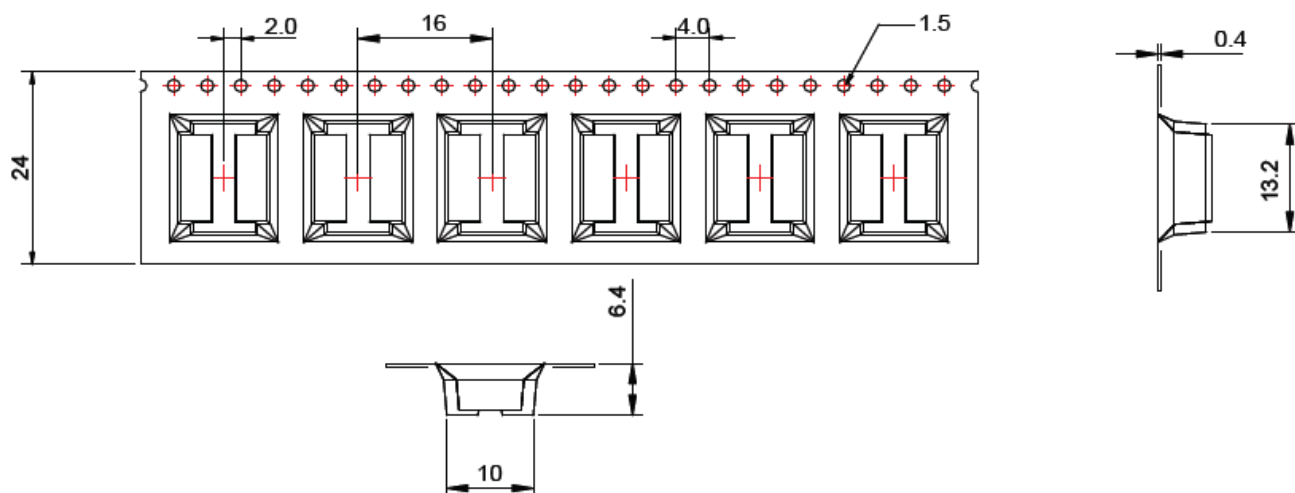
ELECTRICAL SPECIFICATIONS (25°C) :

- TURN RATIOS ($\pm 3\%$) : TX & RX 1CT : 1CT
- INDUCTANCE : PIN 1-3 = 6-8 = 350uH MIN. @100KHz, 0.1Vrms, 8mA DC BIAS.
- INSERTION LOSS (@1MHz-100MHz) : -1.1dB MAX.
- RETURN LOSS (dB MIN.) : @30MHz = -18dB MIN.
@60MHz = -14dB MIN.
@80MHz = -12dB MIN.
- DIFFERENTIAL TO COMMON MODE REJECTION (dB MIN.) : @30MHz = -40dB MIN.
@60MHz = -35dB MIN.
@100MHz = -30dB MIN.
- CROSSTALK (dB MIN.) : @1-100MHz = -30dB MIN.
- CW/W : 28pF MAX.
- L.L : 0.5uH MAX.
- DCR : 1-3 = 6-8 = 0.7Ω MAX.
11-9 = 14-16 = 1.1Ω MAX.
- HI-POT (@1500VAC, 1mA, 60SEC) : PRI.-SEC.
- OPERATING TEMPERATURE RANGE : -40°C ~ +85°C
- MEETS IEEE 802.3 SPECIFICATION
- RoHS COMPLIANT

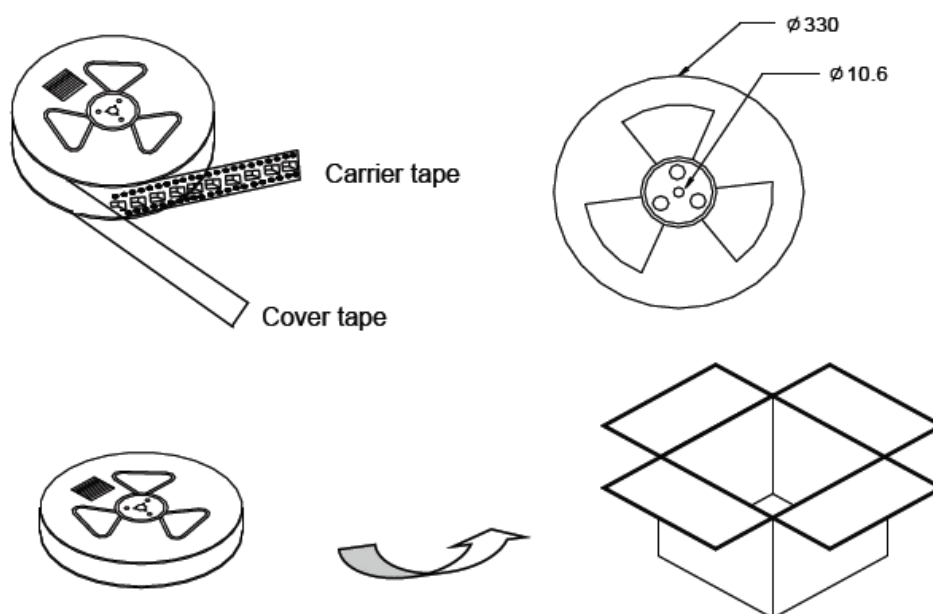
								TITLE 10/100 BASE-TX	
								DWG. NO. ATPL-046DMR	
	RELEASE	02/13 /2017	SHIRLEY	BETTY	BETTY	UNITS: M/M	SAFETY		SHEET 1 OF 1
NO:	DESCRIPTION	DATE	BY	CHK	APPD	DATE 02/13/17	P/N:		DRAW SHIRLEY
REVISIONS									

3. Package :

CARRIER TAPE



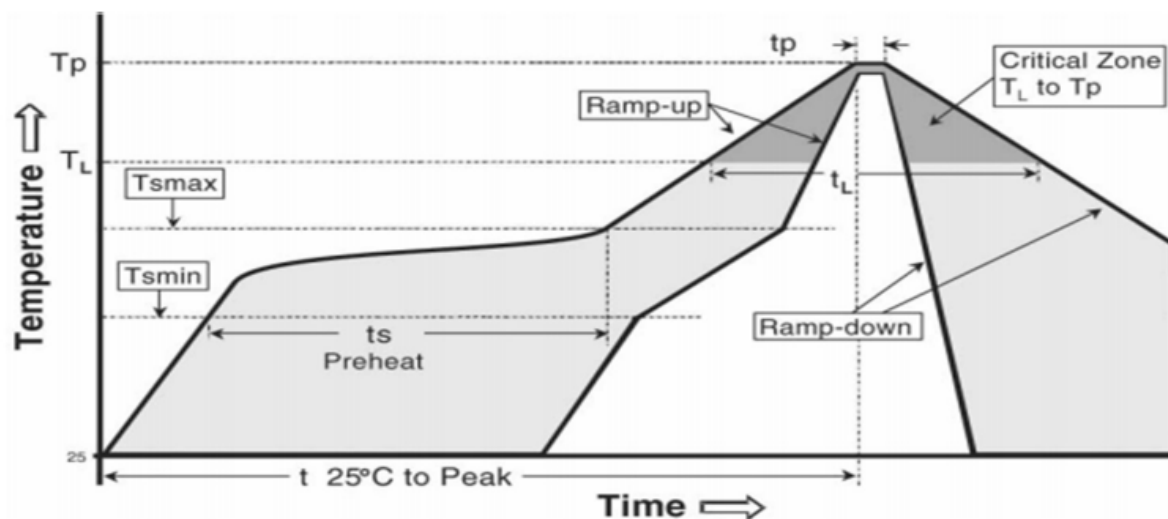
PACKAGE



Product	PCS/Reel	PCS/Box	Product No.	Weight(g/pcs)
SMD 16 PIN Series	600	600*8=4800		

Pb-free Soldering Heat Withstanding Survey

SUGGEST PROFILE



reflow profile

Form-1 (Reference JEDEC J-STD-020D Table 5-2))

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max	3°C/second max
Preheat Temperature Min (Tsmmin)	100°C	150°C
Temperature Min (Tsmax)	150°C	200°C
Time (Tsmmin to Tsmax) (ts)	60-120seconds	60-180seconds
Time maintained above Temperature (TL)	183°C	217°C
Time (tL)	60-150seconds	60-150seconds
Peak Temperature (Tp)	225°C	260°C
Time within 5°C of actual Peak Temperature (Tp) ²	20 seconds	30 seconds
Ramp-down Rate	6°/second max	6°/second max
Time 25°C to Peak Temperature	6minutes max	8minutes max